

SPECIFICATION

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SPEC. NO.: PS-51642-XXXXX-XXX REVISION: B

PRODUCT NAME: 0.5mm PITCH ZIF BACK-FLIP FPC/ FFC CONN. SMT

R/A D/C TYPE

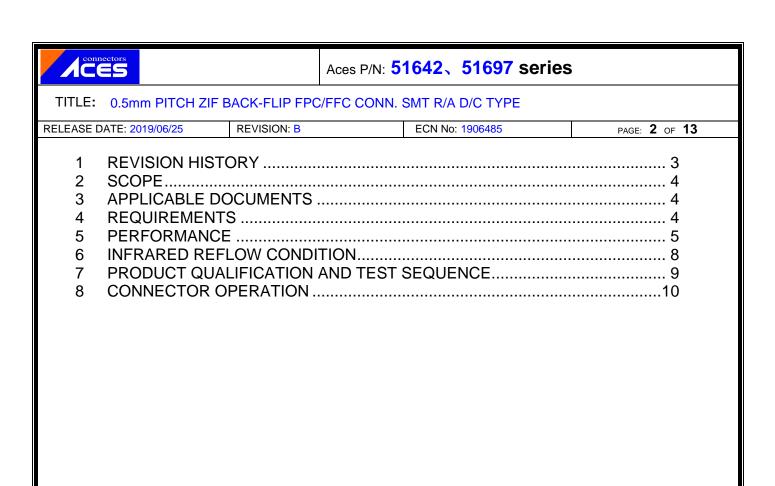
PRODUCT NO: 51642/51697 SERIES

PREPARED: CHECKED: APPROVED:

HUANGYAN BRAVE BRAVE

DATE: DATE:

2019/06/25 2019/06/25 2016/06/25



connectors	Aces P/N: 51642、51697 series	

TITLE: 0.5mm PITCH ZIF BACK-FLIP FPC/FFC CONN. SMT R/A D/C TYPE

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: **3** OF **13**

1 Revision History

Rev.	ECN#	Revision Description	Prepared	Date
0	ECN-1603145	NEW PROJECT SPEC FOR APD1050037	XUBIN	2016/03/02
Α	ECN-1612292	ADD 51697 SERIES	XUBIN	2016/12/26
В	ECN-1906485	CHANGE FPC TO FPC/FFC	HUANGYAN	2019/06/25

CES	Aces P/N: 51642 、	51697 series
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TITLE: 0.5mm PITCH ZIF BACK-FLIP FPC/FFC CONN. SMT R/A D/C TYPE

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: 4 OF 13

2 SCOPE

This specification covers performance, tests and quality requirements for 0.5 mm pitch, ZIF Back-Flip FPC/FFC connector. SMT R/A D/C TYPE

3 APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

- 4.1 Design and Construction
 - 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
 - 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.
- 4.2 Materials and Finish
 - 4.2.1 Contact: High performance copper alloy (Phosphor Bronze)

Finish: (a) Contact Area: Refer to the drawing.

- (b) Under plate: Refer to the drawing.
- (c) Solder area: Refer to the drawing.
- 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.3 Actuator: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.4 Fitting Nail: High performance copper alloy (Brass)

Finish: Refer to the drawing.

4.3 Ratings

- 4.3.1 Working Voltage Less than 36 Volts AC (per pin)
- 4.3.2 Voltage: 50 Volts AC (per pin)
- 4.3.3 Current: DC 0.5 Amperes (per pin)
- 4.3.4 Operating Temperature : -40° to $+85^{\circ}$



TITLE: 0.5mm PITCH ZIF BACK-FLIP FPC/FFC CONN. SMT R/A D/C TYPE

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: **5** OF **13**

5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard					
	Product shall meet requirements of						
Examination of Product	applicable product drawing and	per applicable quality inspection					
	specification.	plan.					
ELECTRICAL							
Item	Requirement	Standard					
		Mate connectors, measure by dry					
Low Level	60 m Ω Max. (initial)per contact	circuit, 20mV Max., 100mA					
Contact Resistance	20 m Ω Max. change allowed	Max.					
		(EIA-364-23)					
		Unmated connectors, apply					
Insulation Resistance	500 M Ω Min.	500 V DC between adjacent					
Insulation Resistance	JOO IVI 12 IVIIII.	terminals.					
		(EIA-364-21)					
		300 VAC Min. at sea level for 1					
Dielectric	No discharge, flashover or	minute.					
Withstanding Voltage	breakdown.	Test between adjacent contacts of					
Vittistationing voltage	Current leakage: 1 mA max.	unmated connectors.					
		(EIA-364-20)					
		Mate connector: measure the					
Temperature Rise		temperature rise at rated current					
	30°C Max. Change allowed	until temperature stable. The					
	Wax. Change allowed	ambient condition is still air at 25°C					
		(EIA-364-70,					
		METHOD1,CONDITION1)					



TITLE: 0.5mm PITCH ZIF BACK-FLIP FPC/FFC CONN. SMT R/A D/C TYPE

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: **6** OF **13**

MECHANICAL						
Item	Requirement	Standard				
Durability	20 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)				
FPC Retention Force	15 gf/pin MIN.	A connector shall be soldered on a board and insert the actuator, pull the FPC at the speed rate of 25.4 ± 3 mm/min.				
Terminal /Housing Retention Force	50 gf MIN.	Operation Speed: 25.4 ± 3 mm/minute. Measure the contact retention force with tester.				
Fitting Nail /Housing Retention Force	50 gf MIN.	Operation Speed: 25.4 ± 3 mm/minute. Measure the contact retention force with tester.				
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)				
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)				



TITLE: 0.5mm PITCH ZIF BACK-FLIP FPC/FFC CONN. SMT R/A D/C TYPE

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: **7** OF **13**

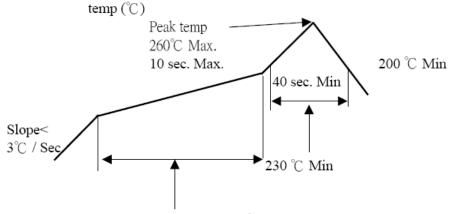
ENVIRONMENTAL						
Item	Requirement	Standard				
Resistance to Reflow Soldering Heat	See Product Qualification and Test Sequence Group 10 (Lead Free)	Pre Heat: 150°C ~180°C, 60~120sec. Heat: 230°C Min., 40sec Min. Peak Temp.: 260°C Max, 10sec Max. IR reflow cycles: 2 times				
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA-364-32, test condition I)				
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)				
Temperature Life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)				
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold plating 3u" for 48 hours. (EIA-364-26)				
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)				
Hand Soldering Temperature Resistance	Appearance: No damage	T≧350°C, 3sec at least.				

Note. Flowing Mixed Gas shell be conduct by customer request.

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: **8** OF **13**

6 INFRARED REFLOW CONDITION

TEMPERATURE CONDITION GRAPH (TEMPERATURE ON BOARD PATTERN SIDE)



Pre-heat Hold time for $150 \sim 180$ °C is $60 \sim 120$ sec.



TITLE: 0.5mm PITCH ZIF BACK-FLIP FPC/FFC CONN. SMT R/A D/C TYPE

RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: **9** OF **13**

7 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test or Examination		Test Group								
		2	3	4	5	6	7	8	9	10
		Test Sequence								
Examination of Product	1、3			1 . 7	1、6	1 \ 4			1	1
Low Level Contact Resistance		1 \ 5	1 \ 4	2、10	2 . 9	2 ` 5			3	
Insulation Resistance				3、9	3 . 8					
Dielectric Withstanding Voltage				4 \ 8	4 · 7					
Temperature Rise	2									
Durability		3								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature Life					5					
Salt Spray(Only For Gold Plating)						3				
Solder ability							1			
FPC Retention Force		2 · 4								
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4



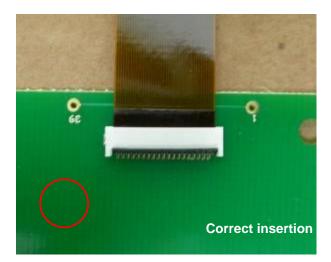
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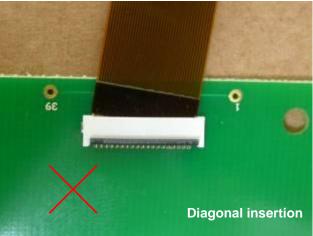
RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: 10 OF 13

8 CONNECTOR OPERATION

Exercise care when handling connectors. Follow recommendations given below.

- A. Please open and close the actuator with the connector is mounted on the P.C.Board, and the FPC inserted. The actuator might not come off from the opening and shutting of the actuator in the state that FPC is not inserted and do not do, please.
- B. FPC Correct insertion verification A visual comparison of the edge of the housing opening and the FPC pattern boundary will prevent diagonal insertion and partial insertion errors.





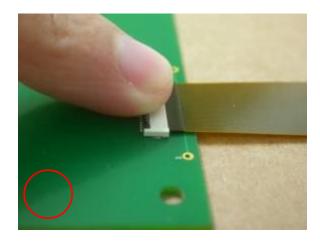


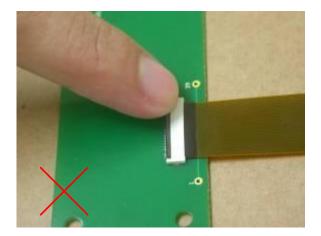
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RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: 11 OF 13

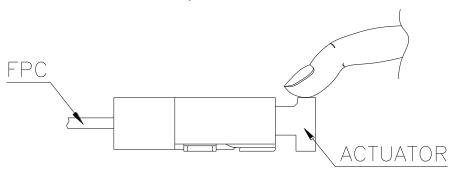
C. Locking

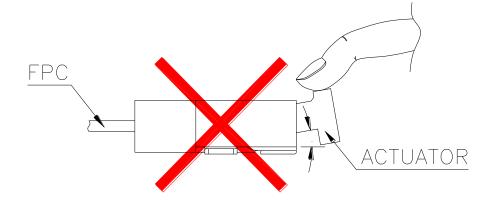
After FPC/FFC insertion, rotate the actuator down to a full stop, pushing it at the center.





About the lock operation When you lock, it is recommended what the actuator does as a whole, and the actuator was shut surely.





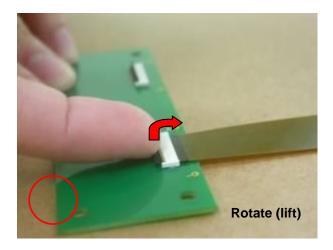


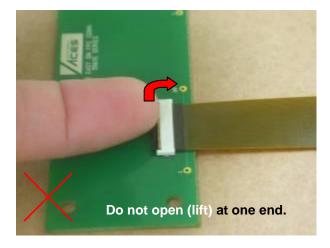
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RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: 12 OF 13

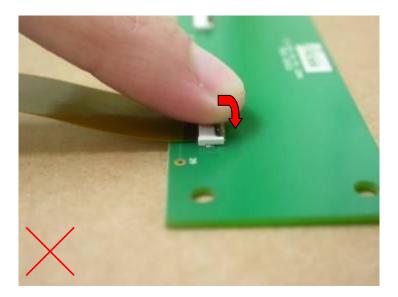
D. Lock release

Carefully rotate the actuator up to 90°, lifting it at the center.





• The actuator opens by rotating it in the direction OPPOSITE to the direction of the insertion of the FPC. DO NOT attempt to open it from the same side as the insertion of the FPC.



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RELEASE DATE: 2019/06/25 REVISION: B ECN No: 1906485 PAGE: 13 OF 13

Precautions

E. This connector is small and thin and requires delicate and careful handling.

Be very careful not to apply any force to the FPC after inserting it.

Otherwise, the connector may become unlocked or the FPC may break.

Fix the FPC, in particular, when loads are applied to it continuously.

Design the FPC layout with care not to bend it sharply near the insertion opening.

